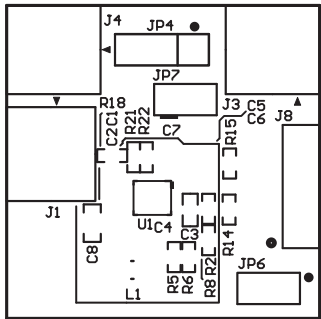
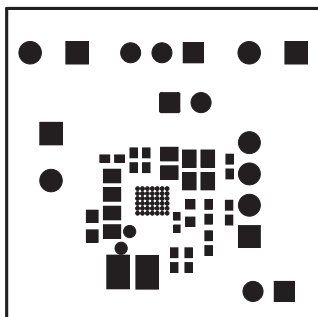


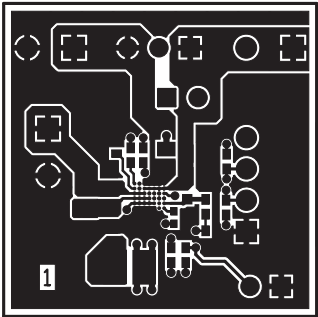
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LAYER NAME = Top Paste	TID #: A0867987		
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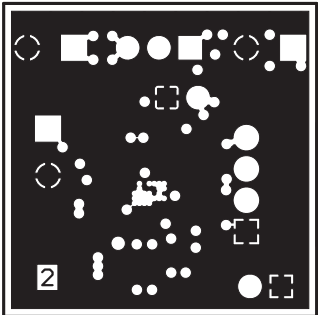
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LAYER NAME = Top Overlay	TID #: A0867987		
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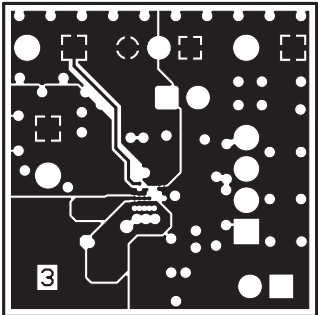
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LAYER NAME = Top Solder	TID #: A0867987		
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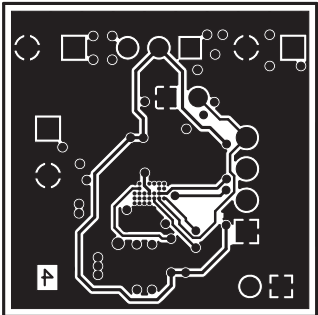
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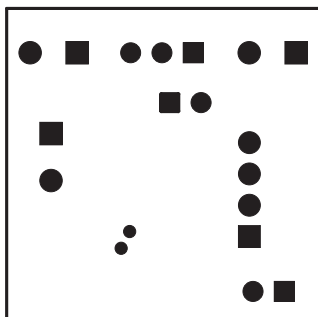
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03042	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: A0867987		
	GENERATED : 12/23/2016 4:14:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03042	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = POWER_SPLIT_PLANE	TID #: A0867987		
	GENERATED : 12/23/2016 4:14:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03042	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: A0867987		
	GENERATED : 12/23/2016 4:14:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03042	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: A0867987		
	GENERATED : 12/23/2016 4:14:12 PM	TEXAS INSTRUMENTS	

SYSTEM
 PULL-UP
 END SYS TAB TAB END
 SUBV CE END
 CE
 END SDA
 END SCL
 END END
 END SM
 PRSSZE Rev-E1
 END OTE

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03042	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: A0867987		
	GENERATED : 12/23/2016 4:14:12 PM	TEXAS INSTRUMENTS	

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